



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814

Examiner: D. Wille

In re Application of:,

Serial No.:

HWANG t al.

10/022,349

Filed: December 20, 2001

or: A SINGLE-CHIP STRUCTURE OF SILICON GERMANIUM

PHOTODETECTOR AND HIGH-SPEED TRANSISTOR

## <u>AMENDMENT</u>

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

This is in response to the Official Action of October 17, 2002, in connection with the above-identified application.

Please amend the above-identified application as follows.

## IN THE CLAIMS:

Please replace claims 20 and 29 with the following amended claims 20 and 29.

20(Amended). A single-chip structure of silicon germanium photodetectors and high-speed transistors comprising:

- a substrate;
- a phototransistor, which is formed on a side of the substrate;
- a high-speed bipolar transistor which is located on the opposite side of the phototransistor on substrate; and
- a separated insulation-layer which separates the phototransistor and the highspeed bipolar transistor, a single-chip structure of the phototransistor and the highspeed bipolar transistor can be completely implemented on a same substrate; and

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